

**22d SPINE Meeting** 

# MATREX - MATERIAL RECORDING EXPERIENCE: CNES MATERIALS DATABASE FOR SPACE APPLICATIONS

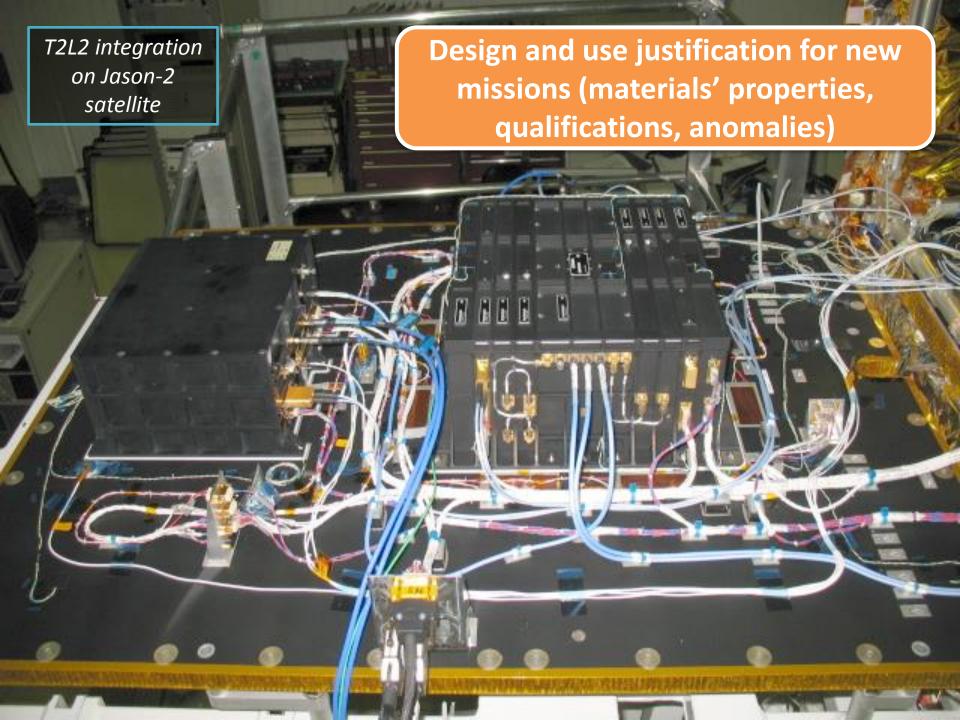
Hélène Combes

23/03/16

Sous-direction Assurance Qualité Service Technologies Matériaux et Procédés CNES Toulouse



22/03/2016







# Risks regarding the procurement (REACh, export control items...)









REGISTRATION, EVALUATION, AUTHORISATION AND RESTRICTION OF CHEMICALS



#### WHY A DB?

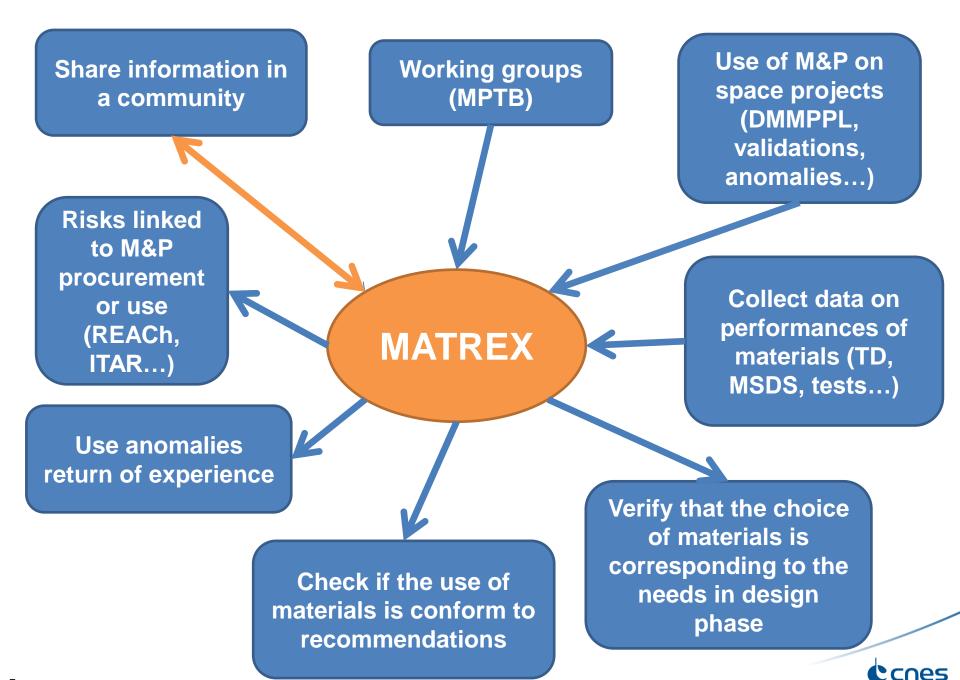
**CAPITALISATION** 

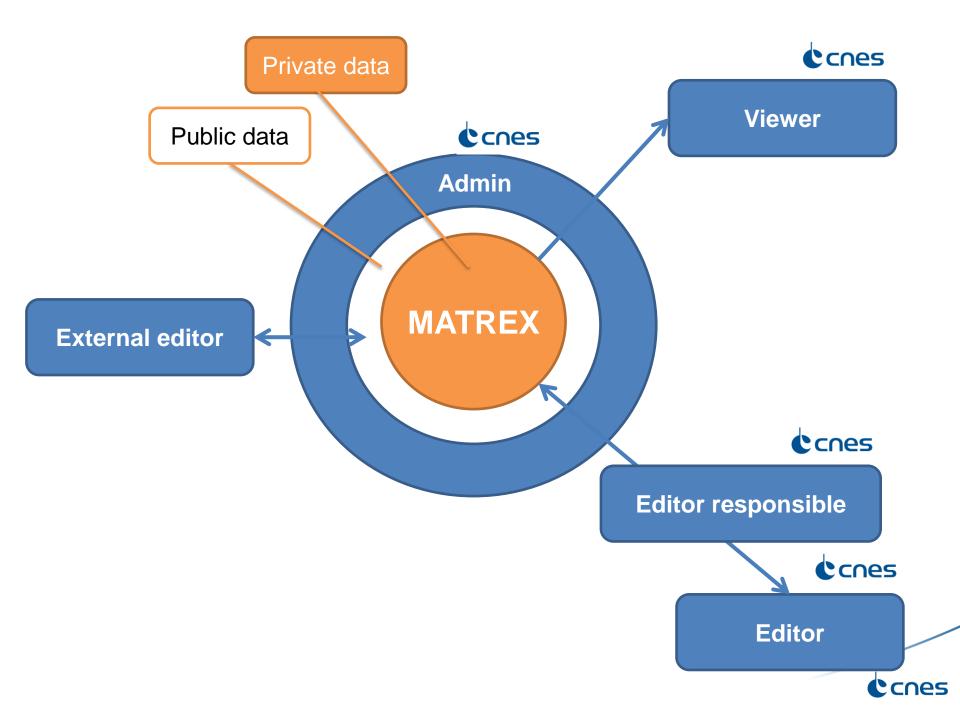
**EFFICIENCY** 

**COST / TIME SAVING** 

**COLLABORATION** 







## **EXISTING DB**

DB	Materials' name	Materials' properties	Toxicity data	Risks	Collabora- tive tool
MAPTIS			X	X	X
ESMAT		X		X	X
MAT DB SYS		X		X	X
MATREX					





**C**cnes



Materials

Process Substances Projects

Suppliers

Links

## bienvenue

0 materials being modified

Le CNES prend toutes les mesures raisonnables pour s'assurer que les informations présentes sur ce site soient exactes et à jour. Toutefois, le CNES, ne donne aucune garantie, expresse ou implicite d'exhaustivité de ces informations ou que celles-ci soient exemptes d'erreurs. Il ne garantit aucune conformité avec les besoins des utilisateurs. Le CNES décline par ailleurs toute responsabilité en cas de dommages résultant de l'utilisation de ces données. L'utilisateur effectue sous sa responsabilité toutes les mesures et vérifications qu'il juge utile. Il informe l'administrateur de la base de toute anomalie qu'il aurait pu constater à ce titre. Le CNES se réserve le droit, à tout moment, de restreindre, suspendre, fermer l'accès de la base, ou d'en modifier sa structure. Il peut également s'il l'estime utile retirer toute information. Le présent site a nullement pour objectif de proposer des prestations ou expertises gracieuses ou payantes. Aucun échange d'information ne pourra être analysé comme tel et engager de ce fait une quelconque responsabilité de son auteur ou du CNES.



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Home	Materials	Process	Substances	Projects	Suppliers	Links
	Material sea	rch				
	Create a mat	terial				
	Search by p	roperties				

Usual name:			Material identifier:	
Keyword:	0 0		SS material class: - Any -	~
	• All the words • At least one wor	d		
▼ <u>Advanced search</u> Family				
Material gro	up: - Any -	~	Chemical family: - Any -	<u>~</u>
Project				
Project nan	ne:			
Substances			Annal ex	
CAS Numb	er:		EC Number:	
List of high concern substanc	CES: CES list EChA Annex XIV EChA Annex XVII EChA Candidate List EChA Proposed for inclusion in Annex XIV	<b>\$</b>		
	Ctrl + left click to select or deselect more than or	one list		
Risks				
	Only the materials with	risks		





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#### ♠ Material Scotch-Weld EC-2216 Gray version 37

eral Information	Properties	Substances	Projects	Suppliers	Documents	Risks	
User detail	s						
User Type:	CNES			~	4	Last modification date: 09/11/2015 Creation date: 13/06/2012	
						Public	
DI I							
→ Risks on m There is at least,		al riek					
There is at least,	one recinic	arrisk					
B 1 4							
Designation						Chemical nature	_
Usual name:	Scotch-We	eld EC-2216 Gray			0	ECSS Material class: 10: Adhesives, coatings, varnishes	~
Others designations:	EC2216				0	Materials family: Thermoset polymers	~
						Chemical family: Epoxy	~
						Other chemical information:	
→ Miscellane	ous informa	tion					
Presentation:	040 1111011114					Application:	
curing epoxy wit	th high peel ar	dhesive EC-2216 nd shear strength			•	- Mechanical bonding - Screw locking	
Scotch-Weld ep certified for aircr	oxy adhesive	EC-2216 B/A has	been labele	d, packaged, t	ested, and	- EEE parts bonding	
(Note: Scotch-W		hesive 2216 B/A i		d for aircraft ar	nd aerospace		
application).							
Means of implem	nentation:					Comments:	
- Mix Ratio (by w	veight): 5 parts	s base / 7 parts a	ccelerator			Cf. ECSS-Q-70-71	
187-1.1 :5- / 4		01. 01	aven. nn			<del>-</del>	

Home







#### Properties joined to Material Scotch-Weld EC-2216 Gray version 37

Propertie *	Value (unit)	Visibility	Comments	Last modification date	User type	Action
Coefficient of thermal expansio	182 (µm/m/K)	Public	40°C to 100°C (ECSS-Q-70-71)	09/10/2015 03:02:13	CNES	<b>[6</b> ]
Coefficient of thermal expansio	45 (µm/m/K)	Public	-100°C to 0°C (ECSS-Q-70-71)	09/10/2015 03:02:13	CNES	<b>6</b>
Glass transition temperature	11.8 (°C)	Public	TMA (ECSS-Q-70-71)	09/10/2015 03:02:13	CNES	<b>6</b>
Maximum use temperature (vacuum)	80 (°C)	Public	Source: ECSS-Q-70-71	09/10/2015 03:02:13	CNES	<b>[</b>
Minimum use temperature (vacuum)	-50 (°C)	Public	Source: ECSS-Q-70-71	09/10/2015 03:02:13	CNES	<b>6</b>
Specific heat capacity	1340 (J/kg/K)	Public	At 0°C (ECSS-Q-70-71)	09/10/2015 03:02:13	CNES	<b>6</b>

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Legal information

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Process Substances Projects

Material >> Material search results >> Scotch-Weld EO-0216

#### Substances joined to Material Scotch-Weld EC-2216 Gray version 38

General information Properties Substances

Projects Suppliers Documents Risks

#### Part A: SCOTCH-WELD 2216 B/A (PARTIE A)

	Revision date	Manufacturer	Source of the MSDS	Action
١	03/12/2014	3M France		6

Identifier	Usual name	CAS	EC	List of high concern	Action
1500	toluene	108-88-3	203-625-9	EChA Annex XVII ; CES	
1643	Kaolin	1332-58-7	310-194-1		
1247	titanium dioxide	13463-67-7	238-875-5	CES list	
1613	3,3'-Oxybis(ethyleneoxy)bis(propylamine)	4246-51-9	224-207-2		
1718	Acides gras, insatures en C18, dimeres,polymeres avec 3,3-(oxybis(2,1- ethanedryloxy))bis(1-propanamine)	68911-25-1		,	

#### Part B: SCOTCH-WELD 2216 B/A (PARTIE B)

ı	Revision date	Manufacturer	Source of the MSDS	Action
ľ	03/12/2014	3M France		6

Identifier	Usual name	CAS number	EC number	List of high concern substances	Action
1643	Kaolin	1332-58-7	310-194-1		
1675	Bisphenol A-epicholrohydrin polymer	25068-38-6			J







Material >> Material search results >> Kapton HN

#### Propriétés joined to Material Kapton HN version 14

Propertie 🏝	Value (unit)	Visibility	Comments	Last modification date	User type	Action
Dielectric strength	276 (kV/mm)	Public	ECSS Q-70-71A. Test: ASTM D194-64 on 25um film at 25°C	30/01/2014 06:04:17	AUTRES	
Dissipation or loss factor (tan delta)	0.003 (-)	Public	D194-64 on 25µm film at 25°C. ECSS Q-70-71A. Test: ASTM D150-64T on 25µm film at 25°C.	30/01/2014 06:04:17	AUTRES	
Electrical resistivity	1e16 (ohms.m)	Public	ECSS Q-70-71A. Test: ASTM D257-61 on 25µm film at 25°C.	30/01/2014 06:04:17	AUTRES	
Relative dielectric constant (Epsilon_r), relative permittivity	3.5 (-)	Public	ECSS Q-70-71A. Test: ASTM D150-64T (1kHz) on 25µm film at 25°C.	30/01/2014 06:04:17	AUTRES	<b>6</b>

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#### WHO CAN ASK FOR AN ACCESS?

#### External users =

Materials experts\* from companies or entities having a contractual link with CNES

+

Originating from EU (access conditioned to specific autorisation if not)

\*on justification



#### MATREX ACCESSIBLE TO CNES PARTNERS

#### 4 levels:

- external editor
- external editor + Règlements & substances
   Access to the module « REACh & substances » and to toxicity data to demonstrate conformity to French Space Act
- external editor + SPIS : access to data shared between users of Spacecraft Plasma Interaction Software (SPIS)
- external editor + Règlements & substances + SPIS



#### MATREX ACCESSIBLE TO CNES PARTNERS

Account request online:

https://matrex.cnes.fr



#### MATREX ACCESSIBLE TO CNES PARTNERS

Communicate on the opening of the DB

Add information: collaborative tool!

MATREX = evolutive tool => please transmit suggestions



#### **OUTLOOK**

=> European materials database (ESMDB)





## matrex



La vérité de demain se nourrit de l'erreur d'hier.

(Antoine de Saint-Exupéry)

